

Plansee Cu-MoCu-Cu Laminate

Category : Metal , Metal Matrix Composite , Nonferrous Metal , Molybdenum Alloy

Material Notes:

A high performance, three-layer composite.Characteristics:High thermal conductivityLow thermal expansionIdeal for heat dissipation applications related to: IGBT modules, RF packages, and LED chips, among others. This laminate is compatible with silicon, GaAs and GaN-based semi-conductor materials.Information provided by Plansee.

Order this product through the following link:

http://www.lookpolymers.com/polymer_Plansee-Cu-MoCu-Cu-Laminate.php

Physical Properties	Metric	English	Comments
Density	9.50 g/cc	0.343 lb/in ³	DIN 3369

Mechanical Properties	Metric	English	Comments
Hardness, Vickers	80 - 120	80 - 120	HV_{0.1}; Cu Layer; ISO 6507-1
Tensile Strength, Yield	630 MPa	91400 psi	0.2%; EN 10002-1
Modulus of Elasticity	195 GPa	28300 ksi	EN 10002-1

Thermal Properties	Metric	English	Comments
CTE, linear	8.00 - 10.0 µm/m-°C	4.44 - 5.56 µin/in-°F	DIN 51045
Thermal Conductivity	>= 170 W/m-K	>= 1180 BTU-in/hr-ft ² -°F	Through Plane; ASTM 1461-01
	>= 260 W/m-K	>= 1800 BTU-in/hr-ft ² -°F	In Plane; ASTM 1461-01
	>= 380 W/m-K	>= 2640 BTU-in/hr-ft ² -°F	Cu Layer; ASTM 1461-01

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